



Integrated Device Technology, Inc.

CMOS SyncFIFO™
64 x 8, 256 x 8, 512 x 8,
1024 x 8, 2048 x 8 and 4096 x 8

IDT72420
IDT72200
IDT72210
IDT72220
IDT72230
IDT72240

FEATURES:

- 64 x 8-bit organization (IDT72420)
- 256 x 8-bit organization (IDT72200)
- 512 x 8-bit organization (IDT72210)
- 1024 x 8-bit organization (IDT72220)
- 2048 x 8-bit organization (IDT72230)
- 4096 x 8-bit organization (IDT72240)
- 12 ns read/write cycle time (IDT72420/72200/72210)
- 15 ns read/write cycle time (IDT72220/72230/72240)
- Read and write clocks can be asynchronous or coincidental
- Dual-Ported zero fall-through time architecture
- Empty and Full flags signal FIFO status
- Almost-empty and almost-full flags set to Empty+7 and Full-7, respectively
- Output enable puts output data bus in high-impedance state
- Produced with advanced submicron CMOS technology
- Available in 28-pin 300 mil plastic DIP and 300 mil ceramic DIP
- For surface mount product please see the IDT72421/72201/72211/72221/72231/72241 data sheet
- Military product compliant to MIL-STD-883, Class B
- Industrial temperature range (-40°C to +85°C) is available, tested to military electrical specifications

DESCRIPTION:

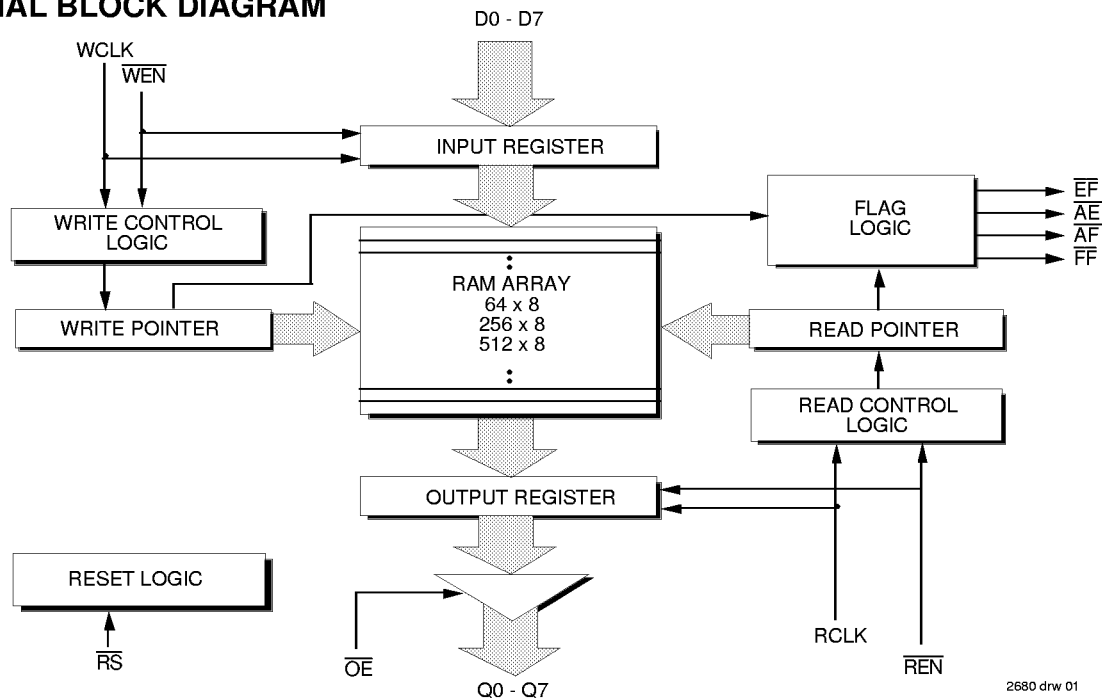
The IDT72420/72200/72210/72220/72230/72240 SyncFIFO™ are very high-speed, low-power First-In, First-Out (FIFO) memories with clocked read and write controls. The IDT72420/72200/72210/72220/72230/72240 have a 64, 256, 512, 1024, 2048, and 4096 x 8-bit memory array, respectively. These FIFOs are applicable for a wide variety of data buffering needs, such as graphics, Local Area Networks (LANs), and interprocessor communication.

These FIFOs have 8-bit input and output ports. The input port is controlled by a free-running clock (WCLK), and a write enable pin (WEN). Data is written into the Synchronous FIFO on every clock when WEN is asserted. The output port is controlled by another clock pin (RCLK) and a read enable pin (REN). The read clock can be tied to the write clock for single clock operation or the two clocks can run asynchronous of one another for dual clock operation. An output enable pin (OE) is provided on the read port for three-state control of the output.

These Synchronous FIFOs have two end-point flags, Empty (EF) and Full (FF). Two partial flags, Almost-Empty (AE) and Almost-Full (AF), are provided for improved system control. The partial (AE) flags are set to Empty+7 and Full-7 for AE and AF respectively.

The IDT72420/72200/72210/72220/72230/72240 are fabricated using IDT's high-speed submicron CMOS technology. Military grade product is manufactured in compliance with the latest revision of MIL-STD-883, Class B.

FUNCTIONAL BLOCK DIAGRAM



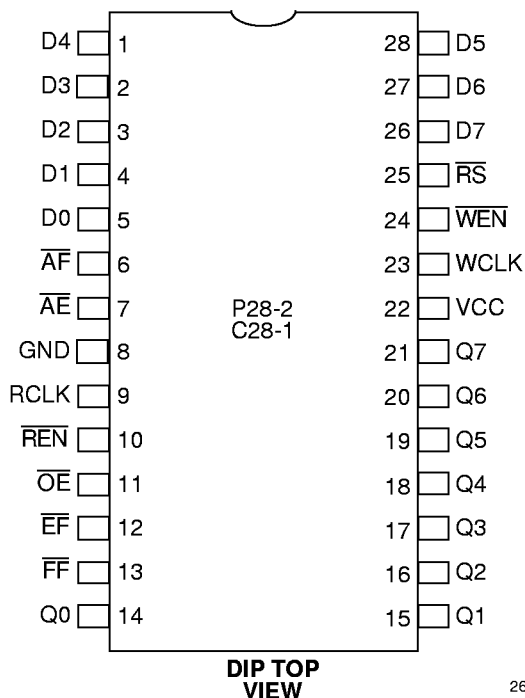
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MILITARY AND COMMERCIAL TEMPERATURE RANGES

NOVEMBER 1996

PIN CONFIGURATION



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PIN DESCRIPTIONS

Symbol	Name	I/O	Description
D0 - D7	Data Inputs	I	Data inputs for a 8-bit bus.
\overline{RS}	Reset	I	When \overline{RS} is set LOW, internal read and write pointers are set to the first location of the RAM array, \overline{FF} and \overline{AF} go HIGH, and \overline{AE} and \overline{EF} go LOW. A reset is required before an initial WRITE after power-up.
WCLK	Write Clock	I	Data is written into the FIFO on a LOW-to-HIGH transition of WCLK when \overline{WEN} is asserted.
\overline{WEN}	Write Enable	I	When \overline{WEN} is LOW, data is written into the FIFO on every LOW-to-HIGH transition of WCLK. Data will not be written into the FIFO if the \overline{FF} is LOW.
Q0 - Q7	Data Outputs	O	Data outputs for a 8-bit bus.
RCLK	Read Clock	I	Data is read from the FIFO on a LOW-to-HIGH transition of RCLK when \overline{REN} is asserted.
\overline{REN}	Read Enable	I	When \overline{REN} is LOW, data is read from the FIFO on every LOW-to-HIGH transition of RCLK. Data will not be read from the FIFO if the \overline{EF} is LOW.
\overline{OE}	Output Enable	I	When \overline{OE} is LOW, the data output bus is active. If \overline{OE} is HIGH, the output data bus will be in a high-impedance state.
\overline{EF}	Empty Flag	O	When \overline{EF} is LOW, the FIFO is empty and further data reads from the output are inhibited. When \overline{EF} is HIGH, the FIFO is not empty. \overline{EF} is synchronized to RCLK.
\overline{AE}	Almost-Empty Flag	O	When \overline{AE} is LOW, the FIFO is almost empty based on the offset Empty+7. \overline{AE} is synchronized to RCLK.
\overline{AF}	Almost-Full Flag	O	When \overline{AF} is LOW, the FIFO is almost full based on the offset Full-7. \overline{AF} is synchronized to WCLK.
\overline{FF}	Full Flag	O	When \overline{FF} is LOW, the FIFO is full and further data writes into the input are inhibited. When \overline{FF} is HIGH, the FIFO is not full. \overline{FF} is synchronized to WCLK.
Vcc	Power		One +5 volt power supply pin.
GND	Ground		One 0 volt ground pin.

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ABSOLUTE MAXIMUM RATINGS⁽¹⁾

Symbol	Rating	Commercial	Military	Unit
VTERM	Terminal Voltage with Respect to GND	-0.5 to +7.0	-0.5 to +7.0	V
TA	Operating Temperature	0 to +70	-55 to +125	°C
TBIAS	Temperature Under Bias	-55 to +125	-65 to +135	°C
TSTG	Storage Temperature	-55 to +125	-65 to +135	°C
IOUT	DC Output Current	50	50	mA

NOTE:

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- Stresses greater than those listed under ABSOLUTE MAXIMUM RATINGS may cause permanent damage to the device. This is a stress rating only and functional operation of the device at these or any other conditions above those indicated in the operational sections of this specification is not implied. Exposure to absolute maximum rating conditions for extended periods may affect reliability.

RECOMMENDED OPERATING CONDITIONS

Symbol	Parameter	Min.	Typ.	Max.	Unit
VCCM	Military Supply Voltage	4.5	5.0	5.5	V
VCCC	Commercial Supply Voltage	4.5	5.0	5.5	V
GND	Supply Voltage	0	0	0	V
V _{IH}	Input High Voltage Commercial	2.0	—	—	V
V _{IH}	Input High Voltage Military	2.2	—	—	V
V _{IL}	Input Low Voltage Commercial & Military	—	—	0.8	V

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CAPACITANCE (TA = +25°C, f = 1.0 MHz)

Symbol	Parameter	Conditions	Max.	Unit
C _{IN} ⁽²⁾	Input Capacitance	V _{IN} = 0V	10	pF
C _{OUT} ^(1, 2)	Output Capacitance	V _{OUT} = 0V	10	pF

NOTES:

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- With output deselected. (\overline{OE} = HIGH)
- Characterized values, not currently tested.

DC ELECTRICAL CHARACTERISTICS

(Commercial: V_{CC} = 5V ± 10%, TA = 0°C to +70°C; Military: V_{CC} = 5V ± 10%, TA = -55°C to +125°C)

Symbol	Parameter	IDT72420 IDT72200 IDT72210 Commercial tCLK = 12, 15, 20, 25, 35, 50 ns			IDT72420 IDT72200 IDT72210 Military tCLK = 20, 25, 35, 50 ns			Units
		Min.	Typ.	Max.	Min.	Typ.	Max.	
I _{LI} ⁽¹⁾	Input Leakage Current (any input)	-1	—	1	-10	—	10	μA
I _{LO} ⁽²⁾	Output Leakage Current	-10	—	10	-10	—	10	μA
V _{OH}	Output Logic "1" Voltage, I _{OH} = -2 mA	2.4	—	—	2.4	—	—	V
V _{OL}	Output Logic "0" Voltage, I _{OL} = 8 mA	—	—	0.4	—	—	0.4	V
I _{CC1} ⁽³⁾	Active Power Supply Current	—	—	80	—	—	100	mA

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Symbol	Parameter	IDT72220 IDT72230 IDT72240 Commercial tCLK = 15, 20, 25, 35, 50 ns			IDT72220 IDT72230 IDT72240 Military tCLK = 25, 35, 50 ns			Units
		Min.	Typ.	Max.	Min.	Typ.	Max.	
I _{LI} ⁽¹⁾	Input Leakage Current (any input)	-1	—	1	-10	—	10	μA
I _{LO} ⁽²⁾	Output Leakage Current	-10	—	10	-10	—	10	μA
V _{OH}	Output Logic "1" Voltage, I _{OH} = -2 mA	2.4	—	—	2.4	—	—	V
V _{OL}	Output Logic "0" Voltage, I _{OL} = 8 mA	—	—	0.4	—	—	0.4	V
I _{CC1} ⁽⁴⁾	Active Power Supply Current	—	—	80	—	—	100	mA

NOTES:

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- Measurements with 0.4 ≤ V_{IN} ≤ V_{CC}.
 - $\overline{OE} \geq V_{IH}$, 0.4 ≤ V_{OUT} ≤ V_{CC}.
 - & 4. Measurements are made with outputs unloaded. Tested at f_{CLK} = 20 MHz.
 - Typical I_{CC1} = 30 + (f_{CLK}*0.5/MHz) + (f_{CLK}*CL*0.02/MHz-pF) mA
 - Typical I_{CC1} = 32 + (f_{CLK}*0.6/MHz) + (f_{CLK}*CL*0.02/MHz-pF) mA
- f_{CLK} = 1 / t_{CLK}
CL = external capacitive load (30 pF typical)

AC ELECTRICAL CHARACTERISTICS

(Commercial: $V_{CC} = 5V \pm 10\%$, $T_A = 0^\circ C$ to $+70^\circ C$; Military: $V_{CC} = 5V \pm 10\%$, $T_A = -55^\circ C$ to $+125^\circ C$)

Symbol	Parameter	Commercial		Comm. & Mil.		Comm.	Comm/Mil	Unit
		72200L12	72200L15	72200L20	72200L25	72200L35	72200L50	
		72210L12	72210L15	72210L20	72210L25	72210L35	72210L50	
		72420L12	72420L15	72420L20	72420L25	72420L35	72420L50	
		Min. Max.	Min. Max.	Min. Max.	Min. Max.	Min. Max.	Min. Max.	
fS	Clock Cycle Frequency	— 83.3	— 66.7	— 50	— 40	— 28.6	— 20	MHz
tA	Data Access Time	2 8	2 10	2 12	3 15	3 20	3 25	ns
tCLK	Clock Cycle Time	12 —	15 —	20 —	25 —	35 —	50 —	ns
tCLKH	Clock High Time	5 —	6 —	8 —	10 —	14 —	20 —	ns
tCLKL	Clock Low Time	5 —	6 —	8 —	10 —	14 —	20 —	ns
tDS	Data Set-up Time	3 —	4 —	5 —	6 —	8 —	10 —	ns
tDH	Data Hold Time	0.5 —	1 —	1 —	1 —	2 —	2 —	ns
tENS	Enable Set-up Time	3 —	4 —	5 —	6 —	8 —	10 —	ns
tENH	Enable Hold Time	0.5 —	1 —	1 —	1 —	2 —	2 —	ns
tRS	Reset Pulse Width ⁽¹⁾	12 —	15 —	20 —	25 —	35 —	50 —	ns
tRSS	Reset Set-up Time	12 —	15 —	20 —	25 —	35 —	50 —	ns
tRSR	Reset Recovery Time	12 —	15 —	20 —	25 —	35 —	50 —	ns
tRSF	Reset to Flag and Output Time	— 12	— 15	— 20	— 25	— 35	— 50	ns
tOLZ	Output Enable to Output in Low-Z ⁽²⁾	0 —	0 —	0 —	0 —	0 —	0 —	ns
tOE	Output Enable to Output Valid	3 7	3 8	3 10	3 13	3 15	3 28	ns
tOHZ	Output Enable to Output in High-Z ⁽²⁾	3 7	3 8	3 10	3 13	3 15	3 28	ns
tWFF	Write Clock to Full Flag	— 8	— 10	— 12	— 15	— 20	— 30	ns
tREF	Read Clock to Empty Flag	— 8	— 10	— 12	— 15	— 20	— 30	ns
tAF	Write Clock to Almost-Full Flag	— 8	— 10	— 12	— 15	— 20	— 30	ns
tAE	Read Clock to Almost-Empty Flag	— 8	— 10	— 12	— 15	— 20	— 30	ns
tSKEW1	Skew time between Read Clock & Write Clock for Empty Flag & Full Flag	5 —	6 —	8 —	10 —	12 —	15 —	ns
tSKEW2	Skew time between Read Clock & Write Clock for Almost-Empty Flag & Almost-Full Flag	22 —	28 —	35 —	40 —	42 —	45 —	ns

NOTES:

1. Pulse widths less than minimum values are not allowed.
2. Values guaranteed by design, not currently tested.

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AC ELECTRICAL CHARACTERISTICS

(Commercial: $V_{CC} = 5V \pm 10\%$, $T_A = 0^\circ C$ to $+70^\circ C$; Military: $V_{CC} = 5V \pm 10\%$, $T_A = -55^\circ C$ to $+125^\circ C$)

Symbol	Parameter	Commercial				Commercial & Military				Comm.		Comm./Mil.		Unit
		72220L12		72220L15		72220L20		72220L25		72220L35		72220L50		
		Min.	Max.	Min.	Max.	Min.	Max.	Min.	Max.	Min.	Max.	Min.	Max.	
fS	Clock Cycle Frequency	—	83.3	—	66.7	—	50	—	40	—	28.6	—	20	MHz
tA	Data Access Time	2	8	2	10	2	12	3	15	3	20	3	25	ns
tCLK	Clock Cycle Time	12	—	15	—	20	—	25	—	35	—	50	—	ns
tCLKH	Clock High Time	5	—	6	—	8	—	10	—	14	—	20	—	ns
tCLKL	Clock Low Time	5	—	6	—	8	—	10	—	14	—	20	—	ns
tDS	Data Set-up Time	3	—	4	—	5	—	6	—	8	—	10	—	ns
tDH	Data Hold Time	.5	—	1	—	1	—	1	—	2	—	2	—	ns
tENS	Enable Set-up Time	3	—	4	—	5	—	6	—	8	—	10	—	ns
tENH	Enable Hold Time	.5	—	1	—	1	—	1	—	2	—	2	—	ns
tRS	Reset Pulse Width ⁽¹⁾	12	—	15	—	20	—	25	—	35	—	50	—	ns
tRSS	Reset Set-up Time	12	—	15	—	20	—	25	—	35	—	50	—	ns
tRSR	Reset Recovery Time	12	—	15	—	20	—	25	—	35	—	50	—	ns
tRSF	Reset to Flag and Output Time	—	12	—	15	—	20	—	25	—	35	—	50	ns
tOLZ	Output Enable to Output in Low-Z ⁽²⁾	0	—	0	—	0	—	0	—	0	—	0	—	ns
tOE	Output Enable to Output Valid	3	7	3	8	3	10	3	13	3	15	3	23	ns
tOHZ	Output Enable to Output in High-Z ⁽²⁾	3	7	3	8	3	10	3	13	3	15	3	23	ns
tWFF	Write Clock to Full Flag	—	8	—	10	—	12	—	15	—	20	—	30	ns
tREF	Read Clock to Empty Flag	—	8	—	10	—	12	—	15	—	20	—	30	ns
tAF	Write Clock to Almost-Full Flag	—	8	—	10	—	12	—	15	—	20	—	30	ns
tAE	Read Clock to Almost-Empty Flag	—	8	—	10	—	12	—	15	—	20	—	30	ns
tSKEW1	Skew time between Read Clock & Write Clock for Empty Flag & Full Flag	5	—	6	—	8	—	10	—	12	—	15	—	ns
tSKEW2	Skew time between Read Clock & Write Clock for Almost-Empty Flag & Almost-Full Flag	22	—	28	—	35	—	40	—	42	—	45	—	ns

NOTES:

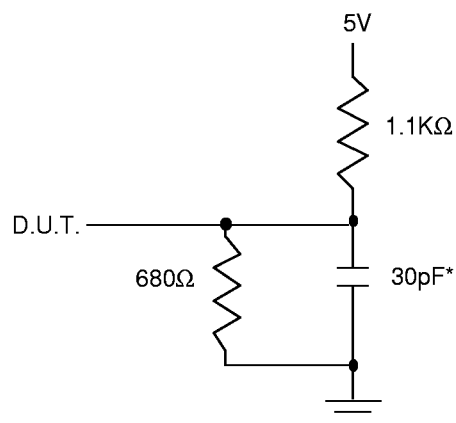
1. Pulse widths less than minimum values are not allowed.
2. Values guaranteed by design, not currently tested.

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AC TEST CONDITIONS

Input Pulse Levels	GND to 3.0V
Input Rise/Fall Times	3ns
Input Timing Reference Levels	1.5V
Output Reference Levels	1.5V
Output Load	See Figure 1

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or equivalent circuit

Figure 1. Output Load

*Includes jig and scope capacitances.

SIGNAL DESCRIPTIONS

INPUTS:

Data In (D₀–D₇) — Data inputs for 8-bit wide data.

CONTROLS:

Reset (RS) — Reset is accomplished whenever the Reset (RS) input is taken to a LOW state. During reset, both internal read and write pointers are set to the first location. A reset is required after power up before a write operation can take place. The Full Flag (FF) and Almost Full Flag (AF) will be reset to HIGH after trSF. The Empty Flag (EF) and Almost Empty Flag (AE) will be reset to LOW after trSF. During reset, the output register is initialized to all zeros.

Write Clock (WCLK) — A write cycle is initiated on the LOW-to-HIGH transition of the write clock (WCLK). Data set-up and hold times must be met in respect to the LOW-to-HIGH transition of the write clock (WCLK). The Full Flag (FF) and Almost Full Flag (AF) are synchronized with respect to the LOW-to-HIGH transition of the write clock (WCLK).

The write and read clocks can be asynchronous or coincident.

Write Enable (WEN) — When Write Enable (WEN) is LOW, data can be loaded into the input register and RAM array on the LOW-to-HIGH transition of every write clock (WCLK). Data is stored in the RAM array sequentially and independently of any on-going read operation.

When Write Enable (WEN) is HIGH, the input register holds the previous data and no new data is allowed to be loaded into the register.

To prevent data overflow, the Full Flag (FF) will go LOW, inhibiting further write operations. Upon the completion of a valid read cycle, the Full Flag (FF) will go HIGH after twFF, allowing a valid write to begin. Write Enable (WEN) is ignored when the FIFO is full.

Read Clock (RCLK) — Data can be read on the outputs on the LOW-to-HIGH transition of the read clock (RCLK). The Empty Flag (EF) and Almost-Empty Flag (AE) are synchronized with respect to the LOW-to-HIGH transition of the read clock (RCLK).

The write and read clocks can be asynchronous or coincident.

Read Enable (REN) — When Read Enable (REN) is LOW, data is read from the RAM array to the output register on the LOW-to-HIGH transition of the read clock (RCLK).

When Read Enable (REN) is HIGH, the output register holds the previous data and no new data is allowed to be loaded into the register.

When all the data has been read from the FIFO, the Empty Flag (EF) will go LOW, inhibiting further read operations. Once a valid write operation has been accomplished, the Empty Flag (EF) will go HIGH after tREF and a valid read can begin. Read Enable (REN) is ignored when the FIFO is empty.

Output Enable (OE) — When Output Enable (OE) is enabled (LOW), the parallel output buffers receive data from the output register. When Output Enable (OE) is disabled (HIGH), the Q output data bus is in a high-impedance state.

OUTPUTS:

Full Flag (FF) — The Full Flag (FF) will go LOW, inhibiting further write operation, when the device is full. If no reads are performed after Reset (RS), the Full Flag (FF) will go LOW after 64 writes for the IDT72420, 256 writes for the IDT72200, 512 writes for the IDT72210, 1024 writes for the IDT72220, 2048 writes for the IDT72230, and 4096 writes for the IDT72240.

The Full Flag (FF) is synchronized with respect to the LOW-to-HIGH transition of the write clock (WCLK).

Empty Flag (EF) — The Empty Flag (EF) will go LOW, inhibiting further read operations, when the read pointer is equal to the write pointer, indicating the device is empty.

The Empty Flag (EF) is synchronized with respect to the LOW-to-HIGH transition of the read clock (RCLK).

Almost Full Flag (AF) — The Almost Full Flag (AF) will go LOW when the FIFO reaches the Almost-Full condition. If no reads are performed after Reset (RS), the Almost Full Flag (AF) will go LOW after 57 writes for the IDT72420, 249 writes for the IDT72200, 505 writes for the IDT72210, 1017 writes for the IDT72220, 2041 writes for the IDT72230 and 4089 writes for the IDT72240.

The Almost Full Flag (AF) is synchronized with respect to the LOW-to-HIGH transition of the write clock (WCLK).

Almost Empty Flag (AE) — The Almost Empty Flag (AE) will go LOW when the FIFO reaches the Almost-Empty condition. If no reads are performed after Reset (RS), the Almost Empty Flag (AE) will go HIGH after 8 writes for the IDT72420, IDT72200, IDT72210, IDT72220, IDT72230 and IDT72240.

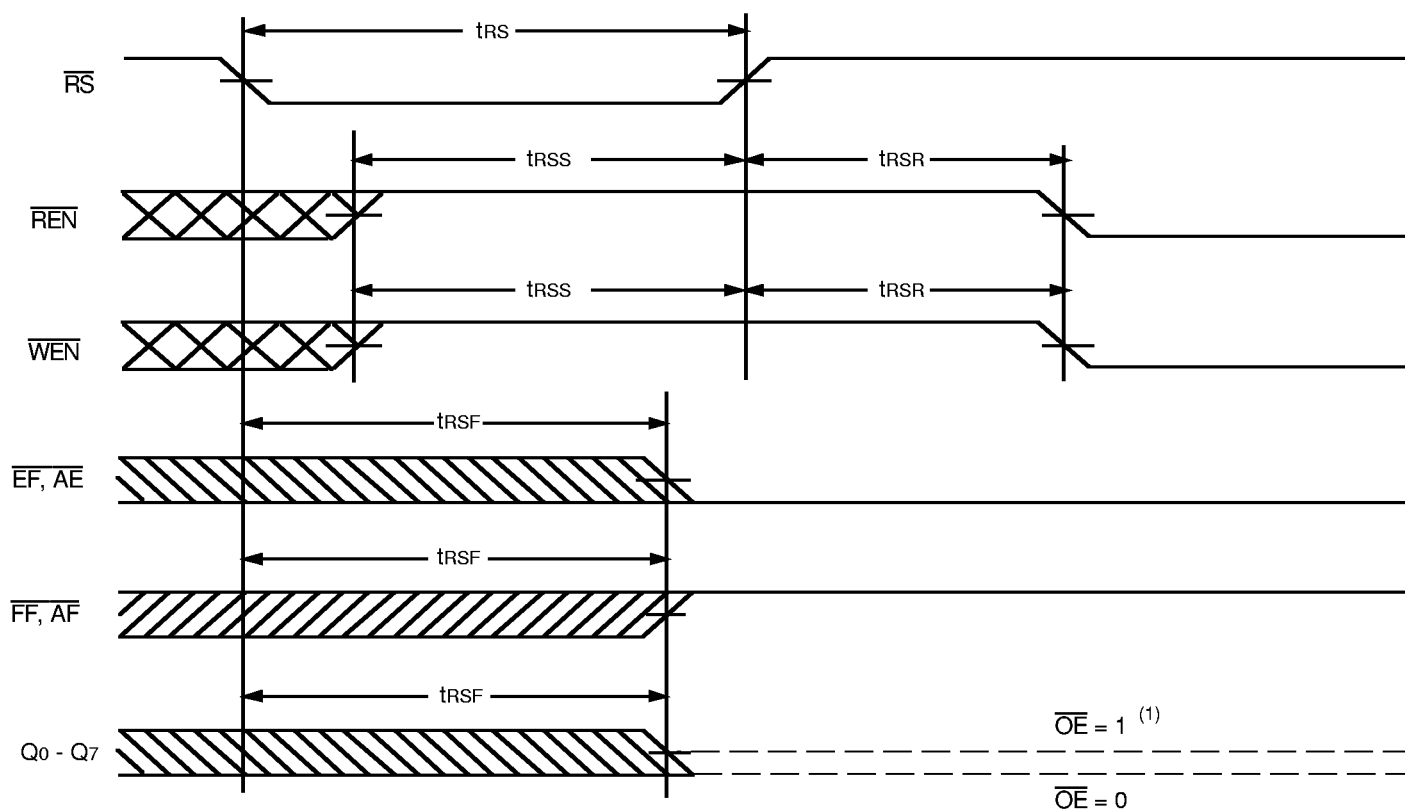
The Almost Empty Flag (AE) is synchronized with respect to the LOW-to-HIGH transition of the read clock (RCLK).

Data Outputs (Q₀–Q₇) — Data outputs for a 8-bit wide data.

TABLE 1: STATUS FLAGS

Number of Words in FIFO						\overline{FF}	\overline{AF}	\overline{AE}	\overline{EF}
IDT72420	IDT72200	IDT72210	IDT72220	IDT72230	IDT72240				
0	0	0	0	0	0	H	H	L	L
1 to 7	1 to 7	1 to 7	1 to 7	1 to 7	1 to 7	H	H	L	H
8 to 56	8 to 248	8 to 504	8 to 1016	8 to 2040	8 to 4088	H	H	H	H
57 to 63	249 to 255	505 to 511	1017 to 1023	2041 to 2047	4089 to 4095	H	L	H	H
64	256	512	1024	2048	4096	L	L	H	H

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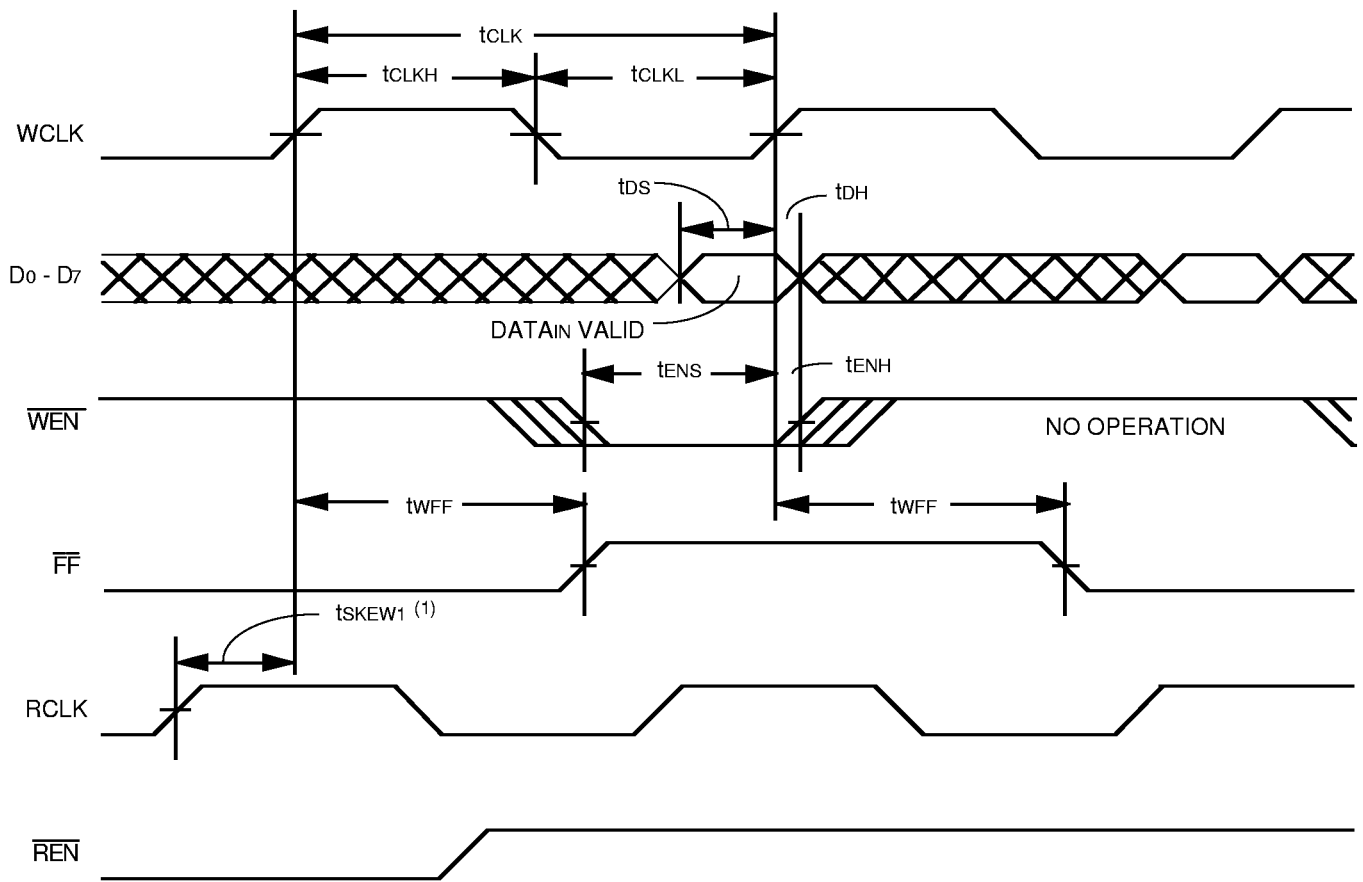


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NOTE:

1. After reset, the outputs will be LOW if $\overline{OE} = 0$ and tri-state if $\overline{OE} = 1$.
2. The clocks (RCLK, WCLK) can be free-running during reset.

Figure 2. Reset Timing

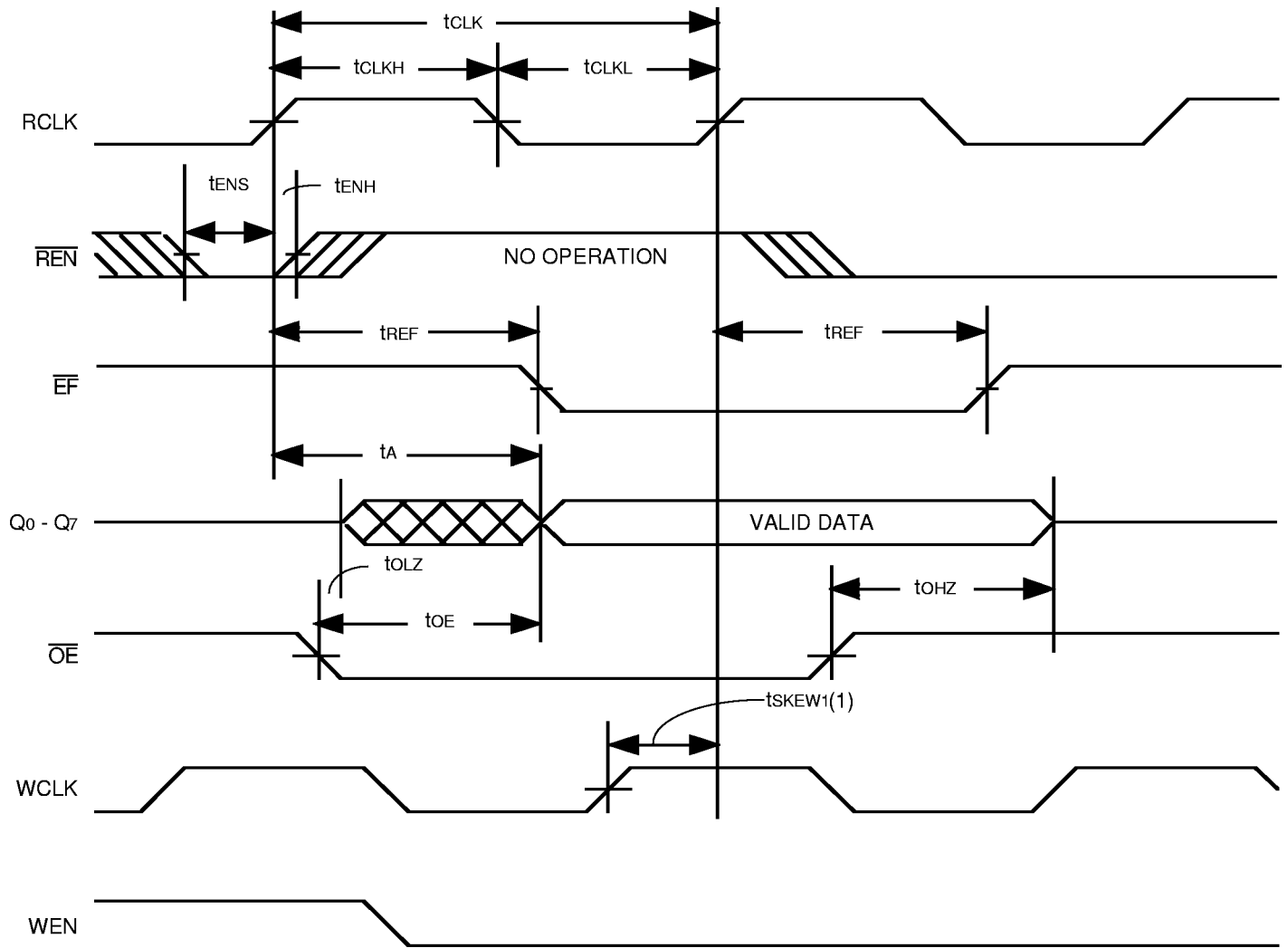


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NOTE:

1. t_{SKEW1} is the minimum time between a rising RCLK edge and a rising WCLK edge for \overline{FF} to change during the current clock cycle. If the time between the rising edge of RCLK and the rising edge of WCLK is less than t_{SKEW1} , then \overline{FF} may not change state until the next WCLK edge.

Figure 3. Write Cycle Timing

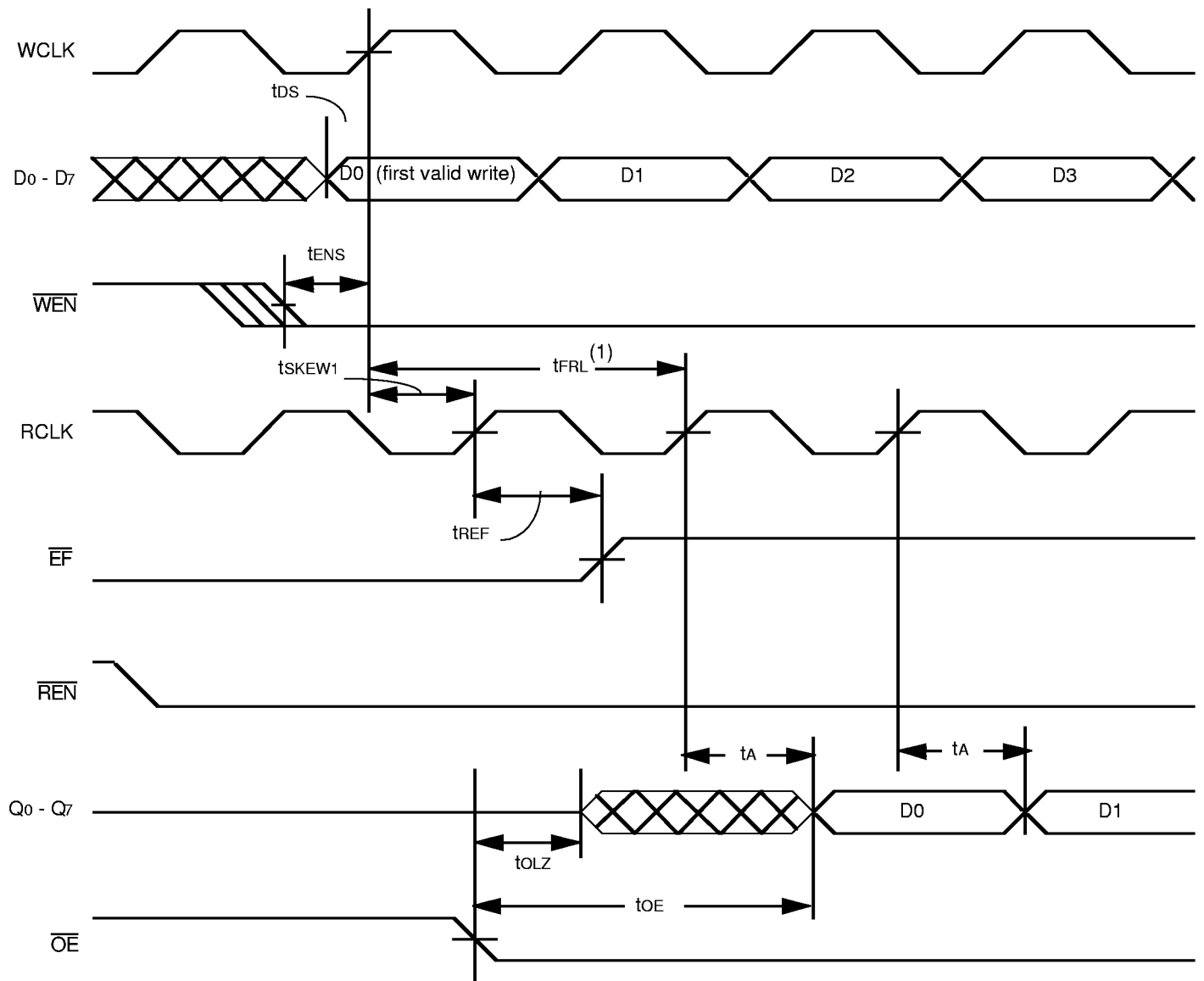


2680 drw 06

NOTE:

1. t_{SKEW1} is the minimum time between a rising WCLK edge and a rising RCLK edge for \overline{EF} to change during the current clock cycle. If the time between the rising edge of WCLK and the rising edge of RCLK is less than t_{SKEW1} , then \overline{EF} may not change state until the next RCLK edge.

Figure 4. Read Cycle Timing

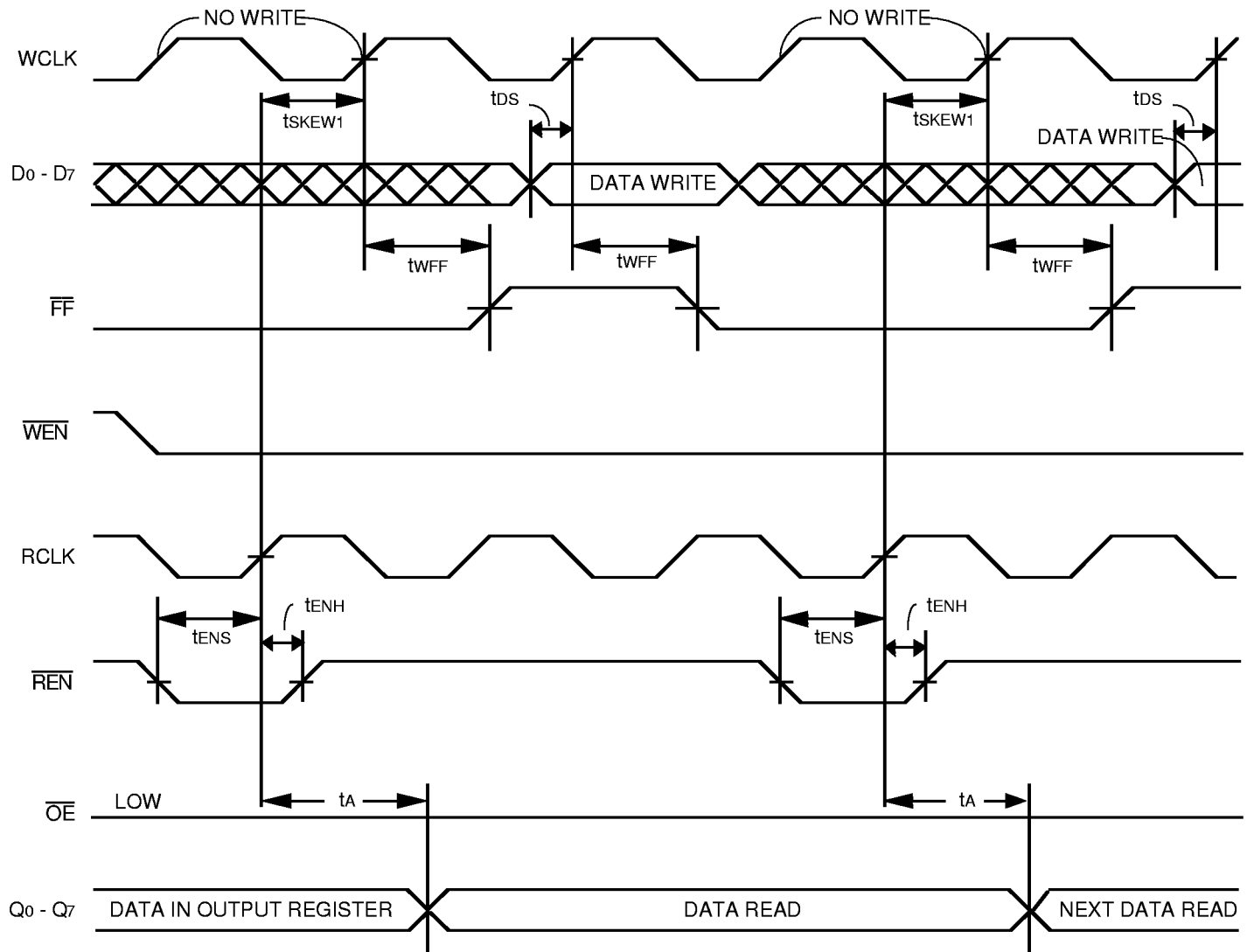


NOTE:

1. When $t_{SKEW1} \geq$ minimum specification, t_{FRL} maximum = $t_{CLK} + t_{SKEW1}$
 $t_{SKEW1} <$ minimum specification, t_{FRL} maximum = $2t_{CLK} + t_{SKEW1}$ or $t_{CLK} + t_{SKEW1}$
 The Latency Timing apply only at the Empty Boundary ($EF = LOW$).

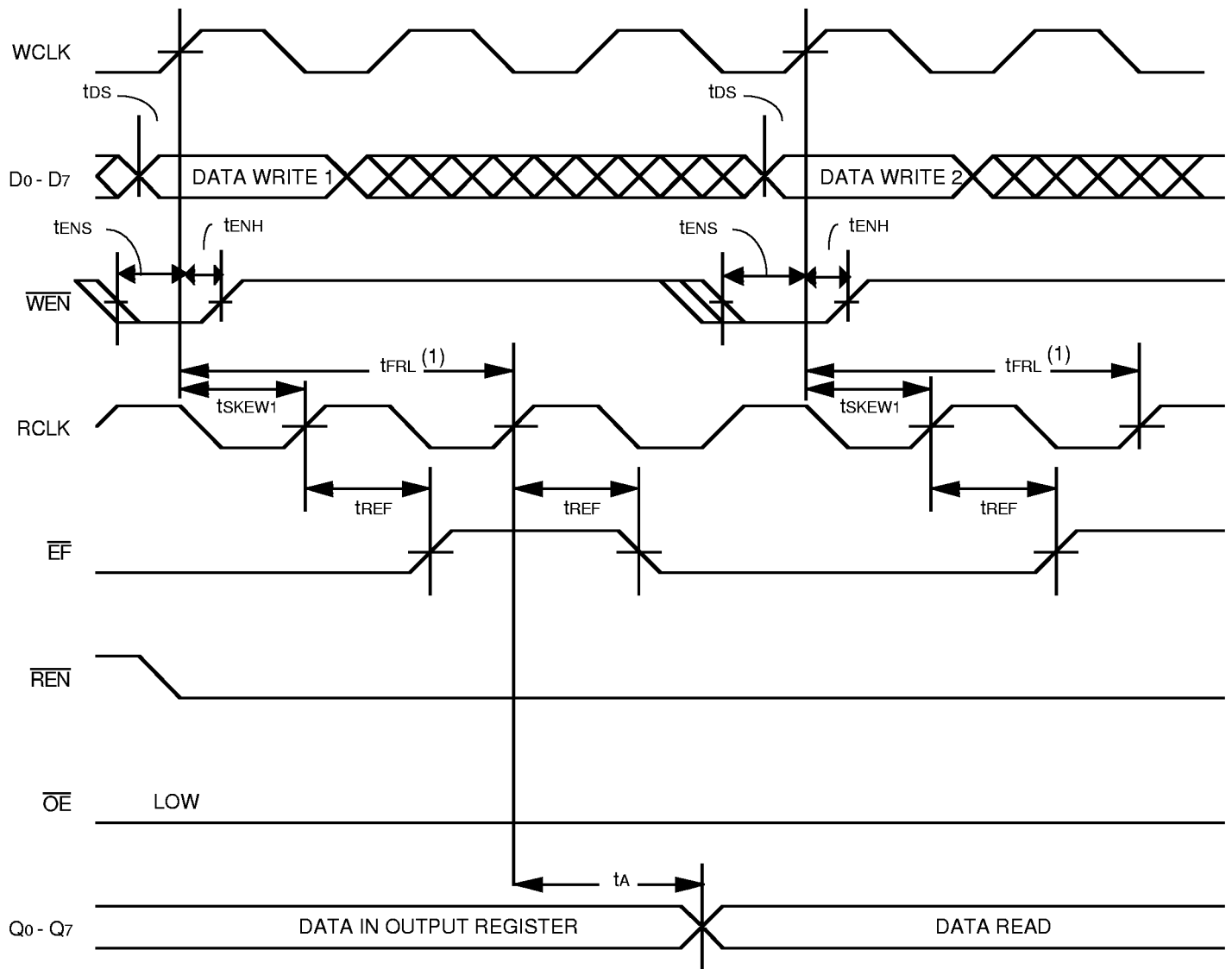
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Figure 5. First Data Word Latency Timing



2680 dnr 08

Figure 6. Full Flag Timing

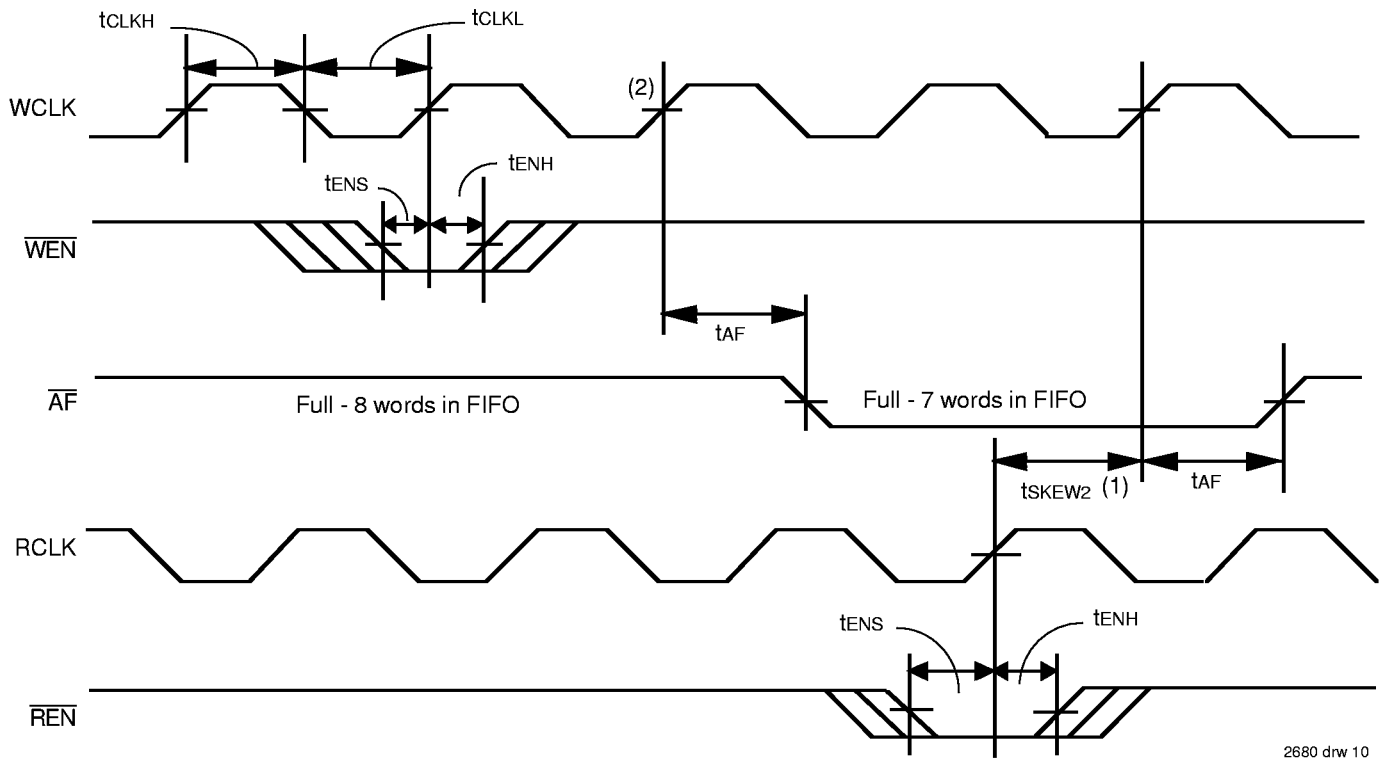


NOTE:

1. When $t_{SKEW1} \geq$ minimum specification, t_{FRL} maximum = $t_{CLK} + t_{SKEW1}$
 $t_{SKEW1} <$ minimum specification, t_{FRL} maximum = $2t_{CLK} + t_{SKEW1}$ or $t_{CLK} + t_{SKEW1}$
 The Latency Timing apply only at the Empty Boundry ($\overline{EF} = \text{LOW}$).

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Figure 7. Empty Flag Timing

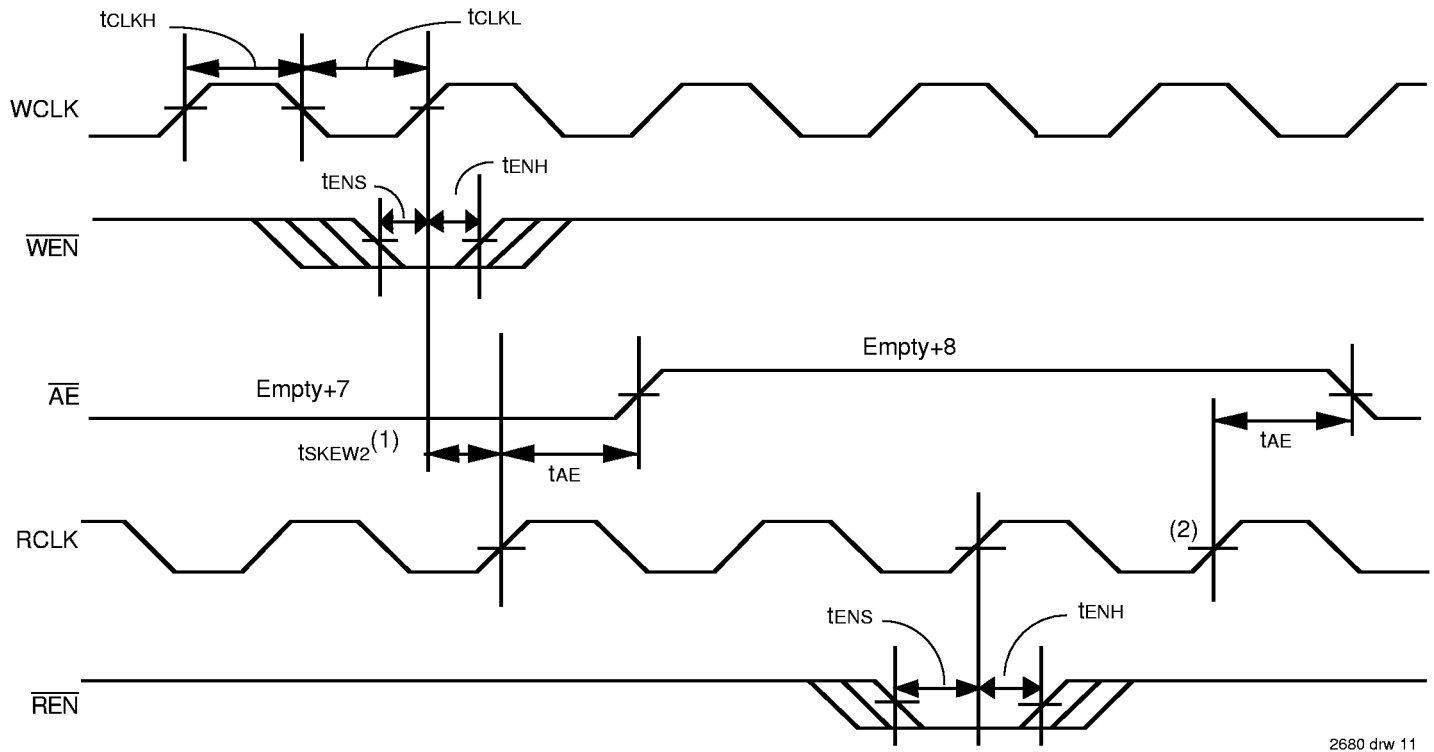


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NOTES:

1. t_{SKEW2} is the minimum time between a rising RCLK edge and a rising WCLK edge for \overline{AF} to change during the current clock cycle. If the time between the rising edge of RCLK and the rising edge of WCLK is less than t_{SKEW2} , then \overline{AF} may not change state until the next WCLK edge.
2. If a write is performed on this rising edge of the write clock, there will be Full - 6 words in the FIFO when \overline{AF} goes LOW.

Figure 8. Almost Full Flag Timing



2680 drw 11

NOTES:

1. t_{SKEW2} is the minimum time between a rising WCLK edge and a rising RCLK edge for \overline{AE} to change during the current clock cycle. If the time between the rising edge of WCLK and the rising edge of RCLK is less than t_{SKEW2} , then \overline{AE} may not change state until the next RCLK edge.
2. If a read is performed on this rising edge of the read clock, there will be Empty - 6 words in the FIFO when \overline{AE} goes LOW.

Figure 9. Almost Empty Flag Timing

OPERATING CONFIGURATIONS

SINGLE DEVICE CONFIGURATION - A single IDT72420/72200/72210/72220/72230/72240 may be used when the application requirements are for 64/256/512/1024/2048/4096 words or less. See Figure 10.

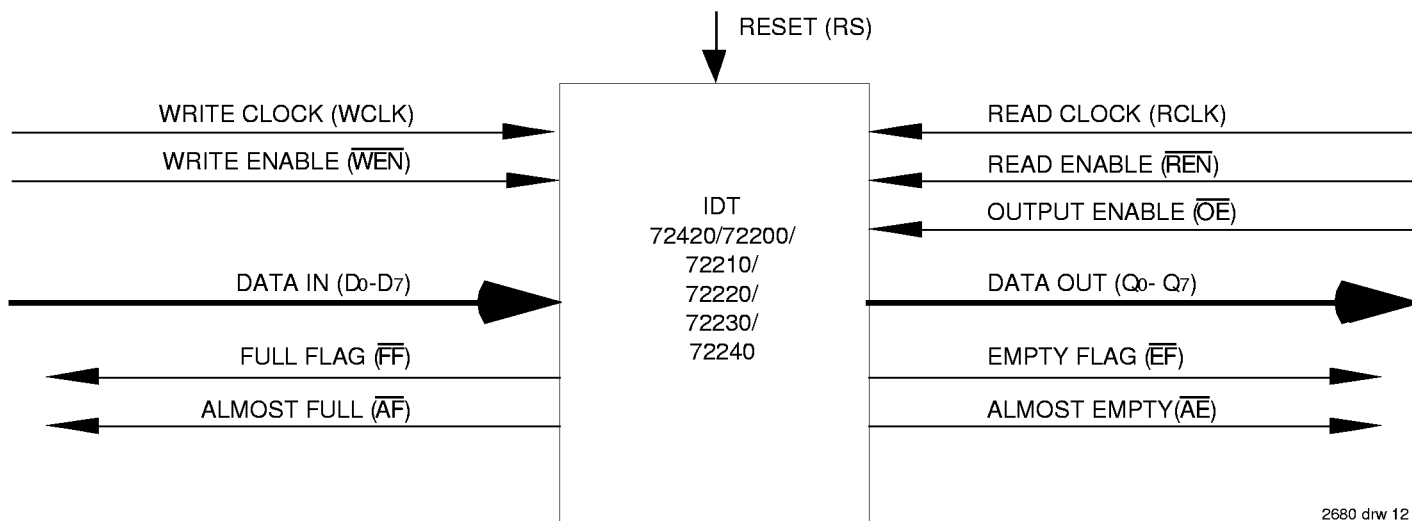


Figure 10. Block Diagram of Single 64 x 8/256 x 8/512 x 8/1024 x 8/2048 x 8/4096 x 8 Synchronous FIFO

WIDTH EXPANSION CONFIGURATION - Word width may be increased simply by connecting the corresponding input control signals of multiple devices. A composite flag should be created for each of the end-point status flags (\overline{EF} and \overline{FF}). The partial status flags (\overline{AE} and \overline{AF}) can be detected from any one

device. Figure 11 demonstrates a 16-bit word width by using two IDT72420/72200/72210/72220/72230/72240s. Any word width can be attained by adding additional IDT72420/72200/72210/72220/72230/72240s.

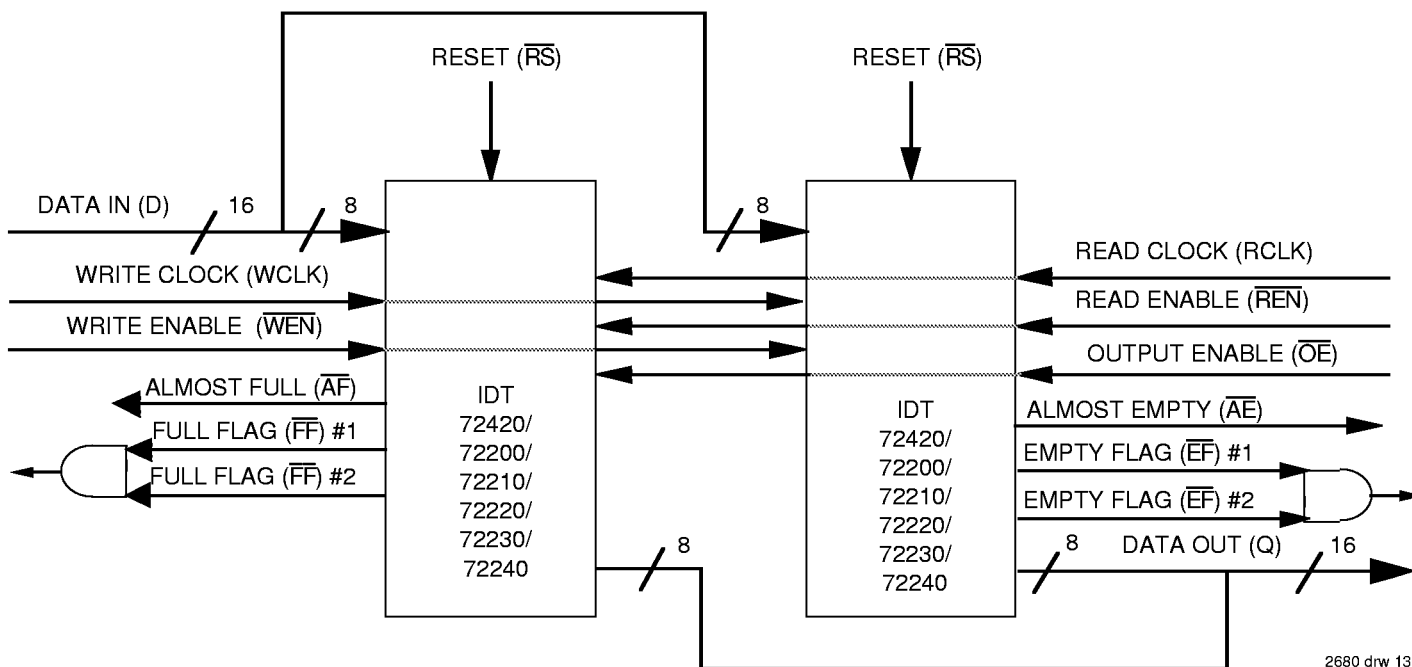


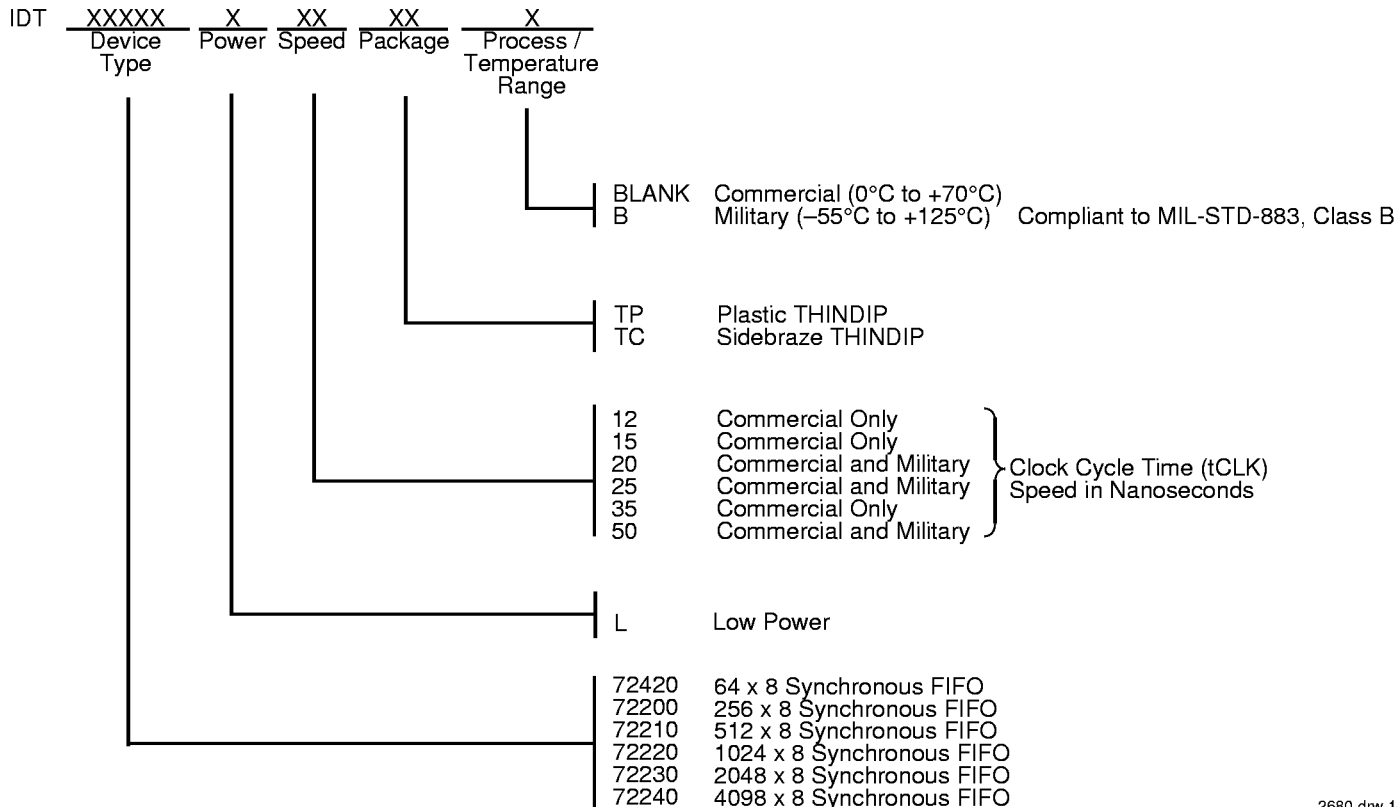
Figure 11. Block Diagram of 64 x 16/256 x 16/512 x 16/1024 x 16/2048 x 16/4096 x 16 Synchronous FIFO Used in a Width Expansion Configuration

DEPTH EXPANSION - The IDT72420/72200/72210/72220/72230/72240 can be adapted to applications when the requirements are for greater than 64/256/512/1024/2048/4096 words. Depth expansion is possible by using expansion logic to direct the flow of data. A typical application would have the

expansion logic alternate data accesses from one device to the next in a sequential manner.

Please see the Application Note "DEPTH EXPANSION IDT'S SYNCHRONOUS FIFOs USING RING COUNTER APPROACH" for details of this configuration.

ORDERING INFORMATION

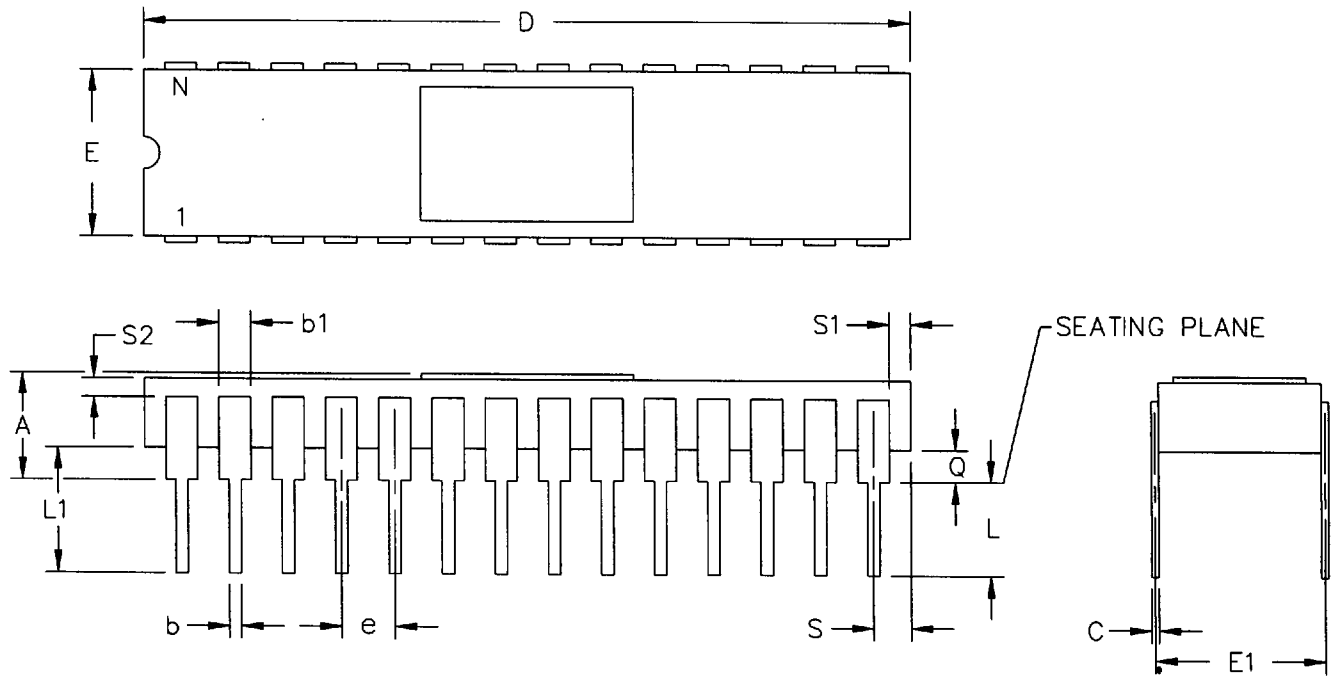


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PACKAGE DIAGRAM OUTLINES

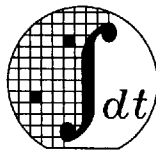
SIDEBRAZE (Continued)

REV	DCN	DESCRIPTION	DATE	APPROVED
02	17564	UPDATED TO STANDARDIZE DWG	4-2-90	S. Thomas
03	19319	ADDED MIL-M-38510 REGISTRATION	10/30/90	D. Guilhamet
04	22238	CHANGED b1 MIN DIMENSION		



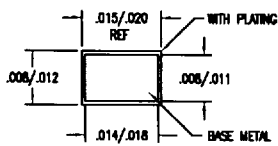
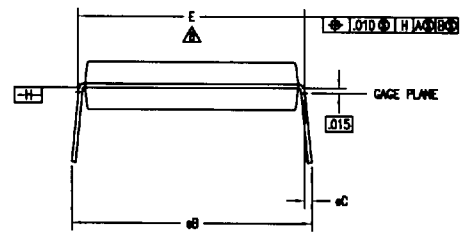
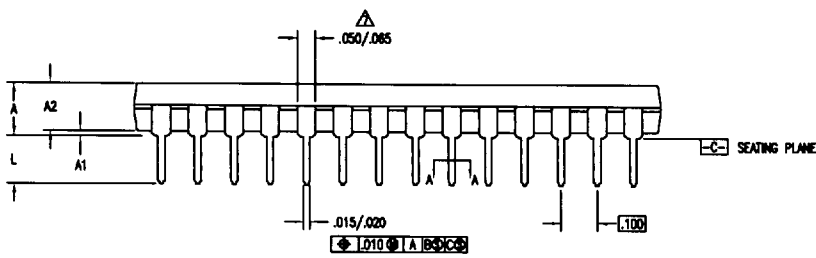
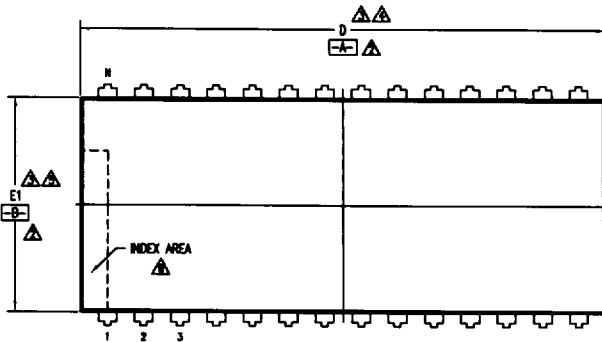
NOTES: (UNLESS OTHERWISE SPECIFIED)

1. ALL DIMENSIONS ARE IN INCHES.
2. BSC - BASIC LEAD SPACING BETWEEN CENTERS.
3. SYMBOL "N" REPRESENTS THE NUMBER OF LEADS.

DWG #	C28-1				CONFIGURATION	EXCEPTIONS		
SYMBOL	MIN	MAX			D-15			
A	.090	.200	MIL-M-38510		NOT REGISTERED			
b	.014	.023	JEDEC					
b1	.045	.060	TOLERANCES UNLESS OTHERWISE SPECIFIED					
C	.008	.015	FRAC DEC ANGLES					
D	1.380	1.420	± - ± - ± -					
E	.220	.310	APPROVALS	DATE	 Integrated Device Technology, Inc. 3236 Scott Blvd., Santa Clara, CA 95051 (408) 727-6116 FAX: (408) 727-2328			
E1	.290	.320	DRAWN <i>Ad</i>	03/90				
e	.100 BSC		CHECKED					
L	.125	.200						
L1	.150	-			28 LD SIDE BRAZE (300 MIL) MKT DWG			
N	28							
Q	.015	.060			SCALE	SIZE	DRAWING NO.	REV
S	.030	.065			N/A	A	PSC-2042	04
S1	.005	-			DO NOT SCALE DRAWING			SHEET
S2	.005	-						36

PACKAGE DIAGRAM OUTLINES
 PLASTIC DIP (Continued)

REVISIONS				
DCM	REV	DESCRIPTION	DATE	APPROVED
27854	05	REDRAW TO JEDEC FORMAT	03/15/95	



SECTION A-A

TOLERANCES UNLESS SPECIFIED		INTEGRATED DEVICE TECHNOLOGY, Inc.	
DECIMAL	ANGULAR	2875 Blunder Way, Santa Clara, CA 95054	PHONE (408) 737-8116
±	±	FAX (408) 462-8274	TELE 910-338-2670
APPROVALS	DATE	TITLE	REV
DRAWN	04/15/95	.800" BODY WIDTH PDIP	05
CHECKED		.100" PITCH	
		SIZE	
		C	
		DRAWING No.	
		PSC-4003	
DO NOT SCALE DRAWING			

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PACKAGE DIAGRAM OUTLINES
 PLASTIC DIP (Continued)

REVISIONS				
DCN	REV	DESCRIPTION	DATE	APPROVED
27854	06	REDRAW TO JEDEC FORMAT	03/15/95	

SYMBOL	P24-2				P28-1				P40-1				P48-1			
	JEDEC VARIATION			NOTE	JEDEC VARIATION			NOTE	JEDEC VARIATION			NOTE	JEDEC VARIATION			NOTE
	AA	MIN	NOM		MAX	AB	MIN		NOM	MAX	AC		MIN	NOM	MAX	
A	.160	-	.185		.160	-	.185		.160	-	.185		.170	-	.200	
A1	.015	-	.035		.015	-	.035		.015	-	.035		.015	-	.035	
A2	.125	.150	.175		.125	.150	.175		.125	.150	.175		.125	.150	.175	
D	1.240	1.250	1.260	3,4	1.420	1.440	1.460	3,4	2.050	2.060	2.070	3,4	2.420	2.435	2.450	3,4
E	.600	.810	.620	8	.600	.610	.620	8	.600	.610	.620	8	.600	.610	.620	8
E1	.530	.540	.550	3,5	.530	.540	.550	3,5	.530	.540	.550	3,5	.530	.545	.560	3,5
eB	.610	-	.670		.610	-	.670		.610	-	.670		.610	-	.670	
eC	.000	-	.040		.000	-	.040		.000	-	.040		.000	-	.040	
L	.120	.135	.150		.120	.135	.150		.120	.135	.150		.120	.135	.150	
N	24				28				40				48			

NOTES:

- ALL DIMENSIONING AND TOLERANCING CONFORM TO ANSI Y14.5M-1982
- DATUMS \square -A \square AND \square -B \square TO BE DETERMINED AT DATUM PLANE \square -H \square
- DIMENSIONS D AND E1 ARE TO BE DETERMINED AT DATUM PLANE \square -H \square
- DIMENSION D DOES NOT INCLUDE MOLD FLASH, PROTRUSIONS OR GATE BURRS. MOLD FLASH, PROTRUSIONS AND GATE BURRS SHALL NOT EXCEED .010 PER SIDE
- DIMENSION E1 DOES NOT INCLUDE INTERLEAD FLASH OR PROTRUSIONS. INTERLEAD FLASH OR PROTRUSIONS SHALL NOT EXCEED .010 PER SIDE
- DETAIL OF PIN 1 IDENTIFIER IS OPTIONAL BUT MUST BE LOCATED WITHIN THE ZONE INDICATED
- LEAD WIDTH DIMENSION DOES NOT INCLUDE DAMBAR PROTRUSION. ALLOWABLE DAMBAR PROTRUSION IS .010 MAXIMUM TOTAL PER LEAD
- DIMENSION E IS MEASURED ON THE OUTSIDE SURFACE OF THE LEADS AT THE GAGE OF .015 BELOW DATUM PLANE \square -H \square
- ALL DIMENSIONS ARE IN INCHES
- THIS OUTLINE CONFORMS TO JEDEC PUBLICATION 95 REGISTRATION MS-011, VARIATION AA, AB, AC & AD

TOLERANCES UNLESS SPECIFIED		Integrated Device Technology, Inc.	
DECIMAL	ANGULAR	3878 Shender Way, Santa Clara, CA 95054	
±	±	PHONE: (408) 737-8118	
DIMS		FAX: (408) 452-8974	
±		TEL: 910-338-3090	
±			
APPROVALS	DATE	TITLE PD PACKAGE OUTLINE	
DRAWN Ad	10/15/93	.600" BODY WIDTH PDIP	
CHECKED		.100" PITCH	
		SIZE	DRAWING No.
		C	PSC-4003
			REV 05
DO NOT SCALE DRAWING			